



WLP – Daisy Chain

Update Aug 6, 2011

Drawing Number System

5	4	168	0
WLP	Pitch	Matrix	Packaging
5 = WLP with balls	3 = 0.3mm (TEG0306)	Daisy Chain Pattern and Ball Matrix	Tray: 0= 4-inch Waffle Pack ("T") Pad Down (WLP) Standard 7= 2-inch Waffle Pack (W) Pad Up (eWLP only) Special 8= 2-inch Waffle Pack ("W") Pad Down (WLP/eWLP) Standard
6= eWLP without balls embedded applications (200um)	4 = 0.4mm (TEG0408)	Example: 16= 16x16	Carrier Tape: 1= T&R Full Reel (E7A or E13A) Pad Down (WLP) 2= Cut Tape ("E") Pad Down (WLP/eWLP) 9= Cut Tape (E) Pad Up (eWLP only)
7= eWLP without balls embedded applications (360um)	5 = 0.5mm (TEG0510)	8= pattern	Wafer format: 3= Sawn Wafer UV Tape and Ring ("U") (WLP/eWLP) 5= Unsawn Wafer, Without Ring (200um thick) eWLP
	6 = 0.65mm (Special)	999 = unsawn wafer	To Be Assigned: 4 and 6



WLP and eWLP Daisy Chain - Part Number

WLP	196	T	.4	C	- DC148	D
Wafer Level Product	Balls	Packing	Pitch	Ball Alloy	Daisy Chain	Die Background Thickness
WLP = with solder ball	4 to 2500	T= 4" Waffle	.3 = 0.3mm (TEG0306)	C= SAC305 (Standard)	DC### Drawing Pattern	Pad Down D = 400um D2= 200um D3= 360um
eWLP = without solder ball		W= 2" Waffle	.4 = 0.4mm (TEG0408)	C1=SAC105 (Special)		Pad Up U2= 200um U3= 360um
		E= On Tape	.5 = 0.5mm (TEG0510)	Blank= Cu Pillar Without Balls eWLP series		251um~349um Not Recommended
		E7A= T&R 7"	.65 = 0.65mm (Special)			
		E13A=T&R 13"				
		U= Sawn Wafer on UV Tape				
		X= Unsawn Wafer				